

DATASHEET

Preliminary

4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER EL817(TH) Series



Features:

- Current transfer ratio
 (CTR: 50~600% at IF= 5mA, VCE= 5V)
- High isolation voltage between input and output (Viso= 5000Vrms)
- Creepage distance> 7.62mm
- Operating temperature up to +110°C
- Compact small outline package
- Pb free and RoHS compliant
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved

Description

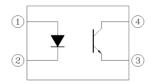
The EL817(TH) series of devices each consist of an infrared emitting diodes, optically coupled to a phototransistor detector.

They are packaged in a 4-pin DIP package and available in wide-lead spacing and SMD option.

Applications

- Programmable controllers
- System appliances, measuring instruments
- Telecommunication equipments
- Home appliances, such as fan heaters, etc.
- Signal transmission between circuits of different potentials and impedances

Schematic



Pin Configuration

- 1. Anode
- 2. Cathode
- 3. Emitter
- 4. Collector



Absolute Maximum Ratings (Ta=25℃)

	Parameter	Symbol	Rating	Unit
	Forward current	I _F	60	mA
Input	Peak forward current (1us, pulse)	I _{FP}	1	А
	Reverse voltage	V_{R}	6	V
	Power dissipation	D	100	mW
	Derating factor (above T _a = 100°C)	P_{D}	2.9	mW/°C
	Power dissipation	_	150	mW
	Derating factor (above $T_a = 100^{\circ}C$)	P _C	5.8	mW/°C
Output	Collector current	Ic	50	mA
	Collector-Emitter voltage	$V_{\sf CEO}$	35	V
	Emitter-Collector voltage	V_{ECO}	6	V
Total Powe	er Dissipation	P _{TOT}	200	mW
Isolation V	'oltage*1	V _{ISO}	5000	V rms
Operating	Temperature	T_OPR	-55 to 110	°C
Storage Te	emperature	T _{STG}	-55 to 125	°C
Soldering	Temperature* ²	T _{SOL}	260	°C

Notes:

^{*1} AC for 1 minute, R.H.= $40 \sim 60\%$ R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

^{*2} For 10 seconds



Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V_{F}	-	1.2	1.4	V	I _F = 20mA
Reverse Current	I _R	-	-	10	μΑ	$V_R = 4V$
Input capacitance	C _{in}	-	30	250	pF	V = 0, f = 1kHz

Output

Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
Collector-Emitter dark	I _{CEO}	-	-	100	nA	$V_{CE} = 20V$, $I_F = 0mA$
current						
Collector-Emitter	BV_CEO	35	_	_	V	$I_{\rm C} = 0.1 \rm mA$
breakdown voltage	D CEO				<u> </u>	10 = 0.1111/1
Emitter-Collector	BV_{ECO}	6	_	_	V	$I_{F} = 0.1 \text{mA}$
breakdown voltage	D v ECO	0			V	IE – U. IIIIA

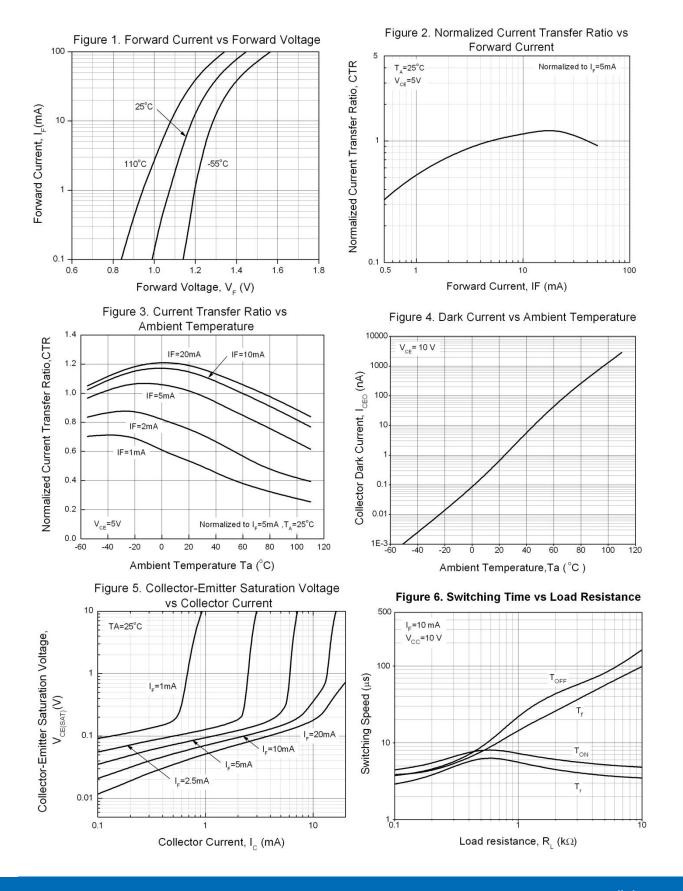
Transfer Characteristics

Parameter		Symbol	Min	Тур.	Max.	Unit	Condition
	EL817		50	-	600	- - - - %	I _F = 5mA ,V _{CE} = 5V
	EL817A		80	-	160		
Current	EL817B		130	-	260		
Transfer	EL817C	CTR	200	-	400		
ratio	EL817D		300	-	600		
	EL817X		100	-	200	-	
	EL817Y		150	-	300		
	Collector-Emitter saturation voltage		-	0.1	0.2	V	$I_F = 20\text{mA}$, $I_C = 1\text{mA}$
Isolation resistance		R _{IO}	5×10 ¹⁰	-	-	Ω	V _{IO} = 500Vdc, 40~60% R.H.
Floating ca	Floating capacitance		-	0.6	1.0	pF	$V_{IO} = 0$, $f = 1MHz$
Cut-off free	Cut-off frequency		-	80	-	kHz	$V_{CE} = 5V$, $I_C = 2mA$ $R_L = 100\Omega$, -3dB
Rise time		t _r	-	4	18	μs	$V_{CE} = 2V, I_{C} = 2mA,$
Fall time	Fall time		-	3	18	μs	$R_L = 100\Omega$

^{*} Typical values at T_a = 25°C



Typical Electro-Optical Characteristics Curves





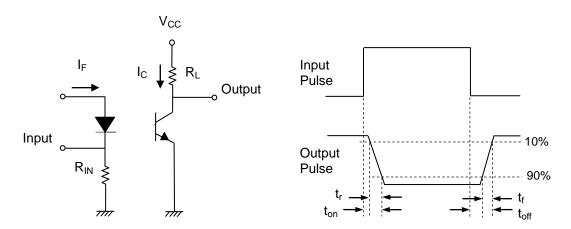


Figure 7. Switching Time Test Circuit & Waveforms



Order Information

Part Number

EL817X(Y)(Z)(TH)-FV

Note

X Y = Lead form option (S, S1, S2, M or none)

= CTR Rank (A, B, C, D, X, Y or none)

Ζ = Tape and reel option (TA, TB, TU, TD or none).

TH = Customer Code

= Lead frame option (F: Iron, None: copper)

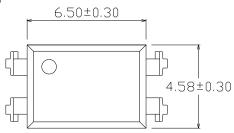
= VDE safety (optional).

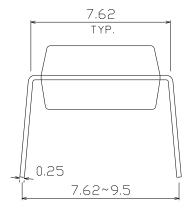
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
М	Wide lead bend (0.4 inch spacing)	100 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel
S2 (TA)	Surface mount lead form (Gull-wing) + TA tape & reel option	1000 units per reel
S2 (TB)	Surface mount lead form (Gull-wing) + TB tape & reel option	1000 units per reel
S (TU)	Surface mount lead form + TU tape & reel option	1500 units per reel
S (TD)	Surface mount lead form + TD tape & reel option	1500 units per reel
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	1500 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	1500 units per reel

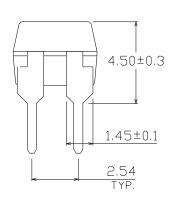


Package Dimension (Dimensions in mm)

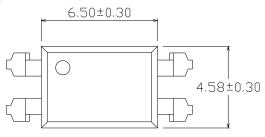
Standard DIP Type

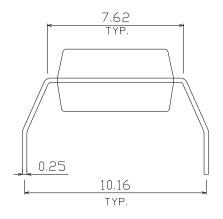


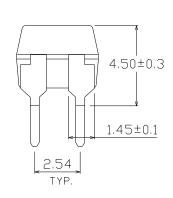




Option M Type

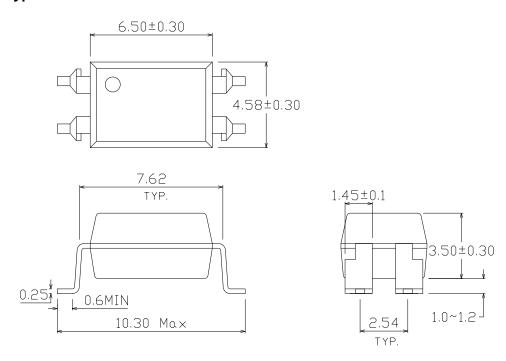




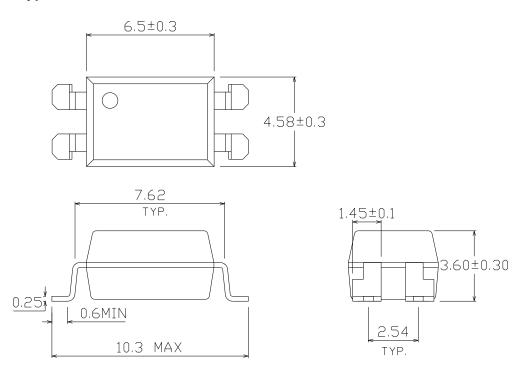




Option S Type

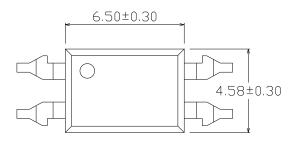


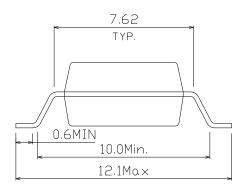
Option S1 Type

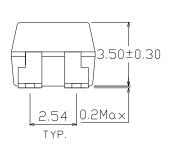




Option S2 Type

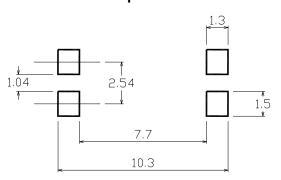




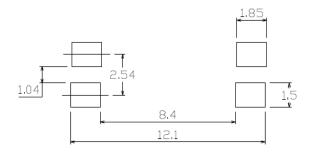


Recommended pad layout for surface mount leadform

For S and S1 option



For S2 option





Device Marking



Notes

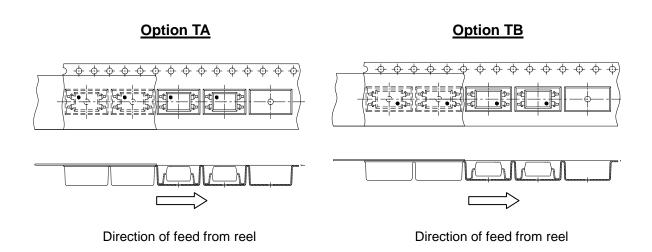
EL denotes EVERLIGHT 817 denotes Device Number

F denotes Factory Code (G: China and Green part)
R denotes CTR Rank (A, B, C, D, X, Y or none)

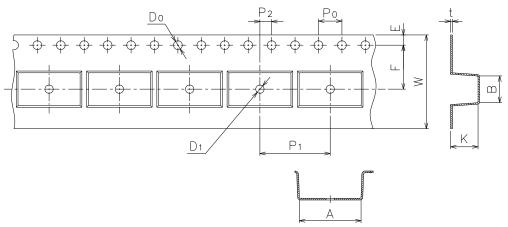
Y denotes 1 digit Year code WW denotes 2 digit Week code V denotes VDE (optional)



Tape & Reel Packing Specifications



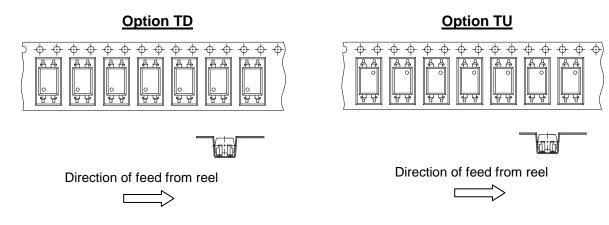
Tape dimensions



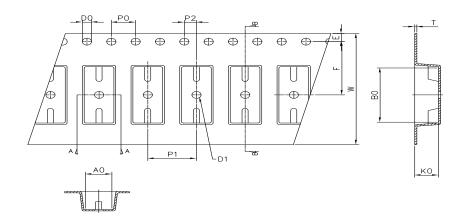
Dimension No.	Α	В	Do	D1	E	F
Dimension (mm) S	10.7±0.1	4.65±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension (mm) S1	10.7±0.1	4.65±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension (mm) S2	12.15±0.1	4.65±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension No.	Ро	P1	P2	t	w	к
Dimension No. Dimension (mm) S	Po 4.0±0.1	P1 12.0±0.1	P2 2.0±0.1	t 0.4±0.1	W 16.0±0.3	K 4.75±0.1
Dimension (mm)						



Tape & Reel Packing Specifications



Tape dimensions



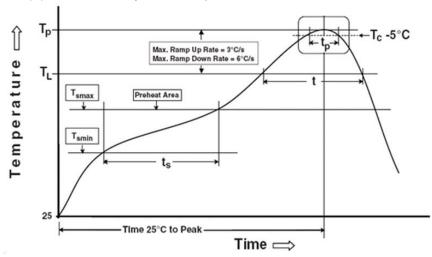
Dimension No.	Ao	Во	Do	D1	E	F
Dimension (mm) S.S1	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension No.	Ро	P1	P2	t	w	Ко



Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin}) 150 °C Temperature max (T_{smax}) 200°C

Time $(T_{smin} \text{ to } T_{smax})$ (t_s) 60-120 seconds 3 °C/second max Average ramp-up rate (T_{smax} to T_p)

Other

Liquidus Temperature (T_L) 217 °C

Time above Liquidus Temperature (t₁) 60-100 sec

Peak Temperature (T_P) Time within 5 °C of Actual Peak Temperature: T_P - 5°C 30 s

Ramp- Down Rate from Peak Temperature 6°C /second max.

Time 25°C to peak temperature 8 minutes max.

Reflow times 3 times

260°C



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